

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Surface mounting technology –
Part 1: Standard method for the specification of surface mounting components
(SMDs)**

**Technique du montage en surface –
Partie 1: Méthode de normalisation pour la spécification des composants
montés en surface (CMS)**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2006 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

IEC Catalogue - webstore.iec.ch/catalogue

The stand-alone application for consulting the entire bibliographical information on IEC International Standards, Technical Specifications, Technical Reports and other documents. Available for PC, Mac OS, Android Tablets and iPad.

IEC publications search - www.iec.ch/searchpub

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and also once a month by email.

Electropedia - www.electropedia.org

The world's leading online dictionary of electronic and electrical terms containing more than 30 000 terms and definitions in English and French, with equivalent terms in 14 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - std.iec.ch/glossary

More than 55 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: csc@iec.ch.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Catalogue IEC - webstore.iec.ch/catalogue

Application autonome pour consulter tous les renseignements bibliographiques sur les Normes internationales, Spécifications techniques, Rapports techniques et autres documents de l'IEC. Disponible pour PC, Mac OS, tablettes Android et iPad.

Recherche de publications IEC - www.iec.ch/searchpub

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et aussi une fois par mois par email.

Electropedia - www.electropedia.org

Le premier dictionnaire en ligne de termes électroniques et électriques. Il contient plus de 30 000 termes et définitions en anglais et en français, ainsi que les termes équivalents dans 14 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

Glossaire IEC - std.iec.ch/glossary

Plus de 55 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: csc@iec.ch.

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Surface mounting technology –
Part 1: Standard method for the specification of surface mounting components
(SMDs)**

**Technique du montage en surface –
Partie 1: Méthode de normalisation pour la spécification des composants
montés en surface (CMS)**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

PRICE CODE
CODE PRIX

U

ICS 31.240

ISBN 978-2-8322-1344-5

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope and object.....	7
1.1 Scope.....	7
1.2 Object.....	7
2 Normative references.....	7
3 Terms and definitions.....	8
4 Requirements for component design and component specifications.....	10
4.1 General requirement.....	10
4.2 Packaging.....	10
4.3 Labelling of product packaging.....	10
4.4 Component marking.....	11
4.5 Storage and transportation.....	12
4.6 Component outline and design.....	12
4.7 Mechanical stress.....	16
4.8 Component reliability assurance.....	16
4.9 Additional requirements for compatibility with lead-free soldering.....	16
5 Specification of assembly process conditions.....	16
5.1 General.....	16
5.2 Securing the component on the substrate prior to soldering.....	18
5.3 Mounting methods.....	19
5.4 Cleaning (where applicable).....	20
5.5 Removal and/or replacement of SMDs.....	21
6 Typical process conditions.....	22
6.1 Soldering processes, temperature/time profiles.....	22
6.2 Typical cleaning conditions for assemblies.....	26
7 Requirements for components and component specifications related to suitability with various mounting processes.....	27
7.1 General.....	27
7.2 Wettability.....	27
7.3 Resistance to dissolution of metallization.....	27
7.4 Resistance to soldering heat.....	27
7.5 Resistance to cleaning solvent.....	28
7.6 Soldering profiles.....	28
7.7 Bonding strength test for the component glue interface test.....	28
Bibliography.....	30
Figure 1 – Example of a component with marked specific orientation put in tape and tray.....	11
Figure 2 – Vacuum pipette, pick-up area and component compartment: Example for a component with a flat surface.....	13
Figure 3 – Coplanarity of terminals.....	13
Figure 4 – Stable seating of component.....	14
Figure 5 – Unstable seating of component.....	14
Figure 6 – Terminals arranged peripherally in two rows.....	14

Figure 7 – Good contrast to component body and surroundings	14
Figure 8 – Component weight/pipette suction strength	15
Figure 9 – Process steps for soldering.....	17
Figure 10 – Process steps for gluing.....	18
Figure 11 – SnPb Vapour phase soldering – Temperature/time profile (terminal temperature).....	22
Figure 12 – Lead-free SnAgCu Vapour phase soldering – Temperature/time profile (terminal temperature).....	23
Figure 13 – Infrared soldering, forced gas convection reflow soldering – Temperature/time profile for SnPb solders.....	24
Figure 14 – Infrared soldering, forced gas convection reflow soldering – Temperature/time profile for lead-free SnAgCu solders.....	25
Figure 15 – Double wave soldering for SnPb and lead-free SnAgCu solder – Temperature/time profile (terminal temperature).....	26
Table 1 – Basic cleaning processes.....	26

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SURFACE MOUNTING TECHNOLOGY –**Part 1: Standard method for the specification
of surface mounting components (SMDs)****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61760-1 has been prepared by IEC technical committee 91: Surface mounting technology.

This second edition cancels and replaces the first edition, published in 1998, and constitutes a technical revision.

The main changes with regard to the previous edition concern:

- requirements related to leadfree soldering;
- extension of the scope to include also components mounted by gluing;
- direct reference to IEC 60068-2-58 for requirements on solderability and resistance to soldering heat;
- classification into categories based on the component's ability to withstand resistance to soldering heat has been deleted.

This bilingual version (2014-02) corresponds to the monolingual English version, published in 2006-04.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/577/FDIS	91/588/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

INTRODUCTION

Specifications for electronic components have in the past been formulated for each component family. The regulations for environmental tests have been selected from IEC 60068 and other IEC and ISO publications. The overriding condition for this procedure was that all components, once installed in a piece of equipment, had to satisfy certain criteria.

The introduction and increasing use of surface mounting components make it necessary to extend the existing requirements to include those arising from processing during assembly.

Irrespective of the component family involved, all components on one and the same side of a printed circuit board are exposed to the same mounting process (see flow charts in Clause 5).

Nevertheless there exists no harmonized standard that prescribes the content of a component specification. It is the purpose of this standard to define the general requirements for component specifications derived from the assembly processes. This is done in three steps.

In the first step general requirements for component specifications and component design related to the handling and placement of the component on the substrate are given (Clause 4). In the second step the definition of reference process conditions as representative of a group of assembly conditions are given (Clauses 5 and 6).

In the third step the additional requirements resulting from these reference process conditions are given (Clause 7).

Mixed technology boards, i.e. boards containing through-hole components and SMDs, require additional consideration with respect to the through-hole components. These may be subject to the same requirements as the SMDs. Persons responsible for drafting specifications for “non-surface mounting components” wishing to include a statement on their ability to withstand surface mounting conditions should use the classifications and tests set out in the present standard.